



Docket No.: 50090-466

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hiroshi HORIBE

Serial No.: 10/050,166

Group Art Unit: 2812

Filed: January 18, 2002

Examiner: not yet assigned

For: SEMICONDUCTOR DEVICE AND WIRE BONDING APPARATUS

REQUEST FOR CORRECTED FILING RECEIPT

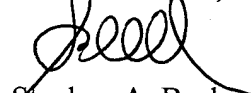
Commissioner for Patents
Washington, DC 20231

Sir:

Attached is a copy of the Filing Receipt received from the U.S. Patent and Trademark Office in the above-referenced application. It is noted that the Foreign Applications Section on the filing receipt is incorrect. Attached is a copy of the Declaration and Power of Attorney, which evidences that the Foreign Applications section should read as: JAPAN 2001-256892 08/27/2001. It is requested that a corrected filing receipt be issued.

Respectfully submitted,

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/050,166	01/18/2002	2812	740 ✓	50090-466	6 ✓	20 ✓	2 ✓

CONFIRMATION NO. 7602

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FEB 19 2002

FILING RECEIPT



OC000000007466897

McDermott, Will & Emery

Date Mailed: 02/13/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Hiroshi Horibe, Tokyo, JAPAN; ✓

Assignment For Published Patent Application

Mitsubishi Denki Kabushiki Kaisha; ✓

Domestic Priority data as claimed by applicant

Foreign Applications

JAPAN 2001-256892 09/27/2001 ✓

If Required, Foreign Filing License Granted 02/12/2002

Projected Publication Date: 03/27/2003

Non-Publication Request: No

Early Publication Request: No

Title

✓ Semiconductor device and wire bonding apparatus

Preliminary Class

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